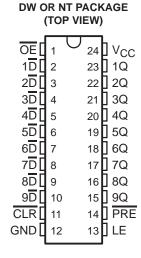
SCBS077A - SEPTEMBER 1991 - REVISED NOVEMBER 1993

- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic 300-mil DIPs (NT)

description

The SN74BCT29844 features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.



The nine latches are transparent D-type latches. When the latch-enable (LE) input is high, the Q outputs are complementary to the inverting data (\overline{D}) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the nine outputs in either a normal logic state (high or low level) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pull-up components.

The output enable (\overline{OE}) does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN74BCT29844 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

	INPUTS							
PRE	CLR	OE	LE	D	Q			
L	Χ	L	X	Х	Н			
Н	L	L	X	X	L			
Н	Н	L	Н	L	Н			
Н	Н	L	Н	Н	L			
Н	Н	L	L	X	Q ₀			
Х	X	Н	Χ	X	Z			

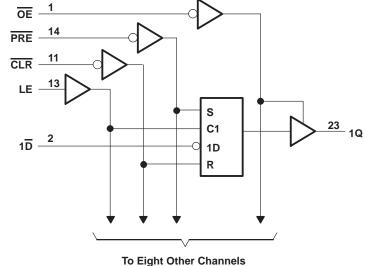


SCBS077A - SEPTEMBER 1991 - REVISED NOVEMBER 1993

logic symbol[†]

OE EN 14 PRE S2 11 R CLR 13 LE C1 2 23 1D 1D 2∇ 1Q 22 3 $2\overline{D}$ 2Q 21 3D **3Q** 5 20 4D 4Q 6 19 5D 5Q 7 18 6D 8 17 7D 7Q 9 16 8D 8Q 10 15 9D 9Q

logic diagram (positive logic)



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	\ldots $-0.5\ V$ to 7 V
Input voltage range, V _I (see Note 1)	\dots $-0.5\ V$ to 7 V
Voltage range applied to any output in the disabled or power-off state, V _O	\dots $-0.5\ V$ to 7 V
Voltage range applied to any output in the high state, V _O	\dots – 0.5 V to V _{CC}
Input clamp current, I _{IK} (V _I < 0)	–30 mA
Current into any output in the low state, I _O	96 mA
Operating free-air temperature range	0°C to 70°C
Storage temperature range	\dots -65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "recommended operating conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			8.0	V
lik	Input clamp current			-18	mA
lOH	High-level output current			-24	mA
lOL	Low-level output current			48	mA
TA	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2	V
N/	V 45V	$I_{OH} = -15 \text{ mA}$	2.4			.,
Voн	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			V
V	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.7			V
V _{OL}	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 48 \text{ mA}$		0.42	0.55	V
lį	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1	mA
l _{IH}	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V	-10		-75	μΑ
I _I L	$V_{CC} = 5.5 \text{ V},$	V _I = 0.5 V			-0.2	mA
los [‡]	$V_{CC} = 5.5 \text{ V},$	VO = 0	-75		-275	mA
lozh	$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			20	μΑ
lozL	V _{CC} = 5.5 V,	V _O = 0.5 V			-20	μΑ
ICCL	V _{CC} = 5.5 V,	Outputs open		3	7	mA
ІССН	V _{CC} = 5.5 V,	Outputs open		24	35	mA
I _{CCZ}	$V_{CC} = 5.5 \text{ V},$	Outputs open		3	7	mA
C _i	$V_{CC} = 5 V$,	$V_{\parallel} = 2.5 \text{ V or } 0.5 \text{ V}$		5		pF
Co	$V_{CC} = 5 V$,	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$		8		pF

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V _{CC} =	V _{CC} = 5 V, T _A = 25°C		MAX	UNIT
			MIN MAX				
		PRE low	4		4		
t _w	Pulse duration	CLR low	4		4		ns
		LE high	4		4		
	Octor Constitute haters LEI	High or low	2.5		2.5		ns
t _{su}	Setup time, data before LE↓	PRE or CLR inactive	2		2		
	Held Considers of the LE	High	2		2		
t _h Hole	Hold time, data after LE↓	Low	3		3		ns

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

SN74BCT29844 9-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS SCBS077A - SEPTEMBER 1991 - REVISED NOVEMBER 1993

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Note 2)

PARAMETER	FROM	TO	V _{CC} = 5 V, T _A = 25°C			MIN MA	MAX	UNIT
	(INPOT)	(INPUT) (OUTPUT)		TYP	MAX			
^t PLH	σI	0	1.8	5	7.3	1.8	9	
t _{PHL}	U	Q	2.2	5	7	2.2	7.8	ns
^t PLH		0	2.1	5	7	2.1	8.2	
t _{PHL}	LE	LE Q	2.7	4.5	6.9	2.7	7.5	ns
^t PLH	PRE	0	1.5	4.5	6.7	1.5	8	
^t PHL	PRE	Q	2.2	4.5	6.2	2.2	6.4	ns
^t PLH	CLR	0	2.1	4.7	6.5	2.1	7.3	
t _{PHL}	CLR	Q	2.4	5.3	7.7	2.4	8.9	ns
^t PZH	ŌĒ	0	2.1	5.2	7.6	2.1	9.3	
t _{PZL}	OE	Q	4.7	8.1	10.6	4.7	12.2	ns
^t PHZ	ŌĒ	Q	2.1	4.3	5.8	2.1	6.6	ns
tPLZ	OE	3	1.5	4.3	6	1.5	6.8	110

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
SN74BCT29844DW	OBSOLETE	SOIC	DW	24	TBD	Call TI	Call TI
SN74BCT29844NT	OBSOLETE	PDIP	NT	24	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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